

A

A

B

B

C

C

D

D

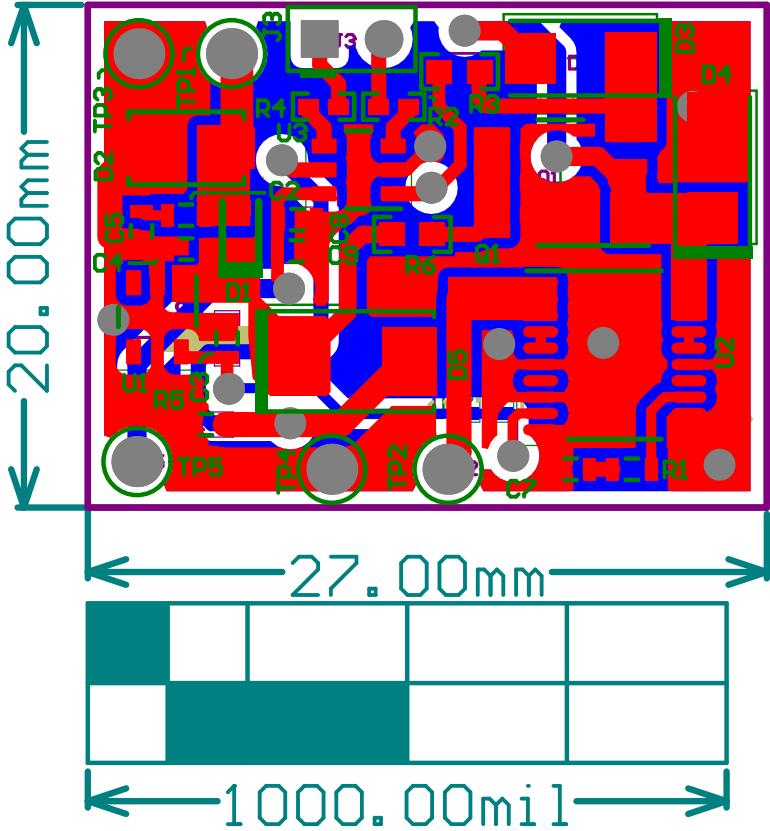
- Z21

■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- Z22

■ These assemblies are ESD sensitive. ESD precautions shall be observed.
- Z23

■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24

■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANTS

(No Variations)

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
[2noit3i:V uoN] :TNAIRAV Y_J8M322A

ALL PARTS ARE TO BE PLACED ON TOP OF BOARD	BOARD # TIDA-020023-01	DATE: E1	SUN 11/08/2023 10:00 AM
LAYER NAME = Bottom	TID #: 020023-01	Bottom Assembly	
PLT NAME = IMAX11	Composite Plot	GENERATED: 11/08/2023 10:00 AM	TEXAS INSTRUMENTS

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

THIS IS NOT AN IMPEDANCE CONTROL BOARD.
ALL VIAS ARE NON _TENTED.

DESIGN INFORMATION

MIN. TRACK WIDTH: 15 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

☐ FR-408

☒ FR-4 High Tg

☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHERARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORECERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YESBARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

PROJECT TITLE:
TIDA-020023

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-020023_PCBLayout.PcbDoc

ENGINEER:
Sandeep Tallada

LAYOUT BY:
Sandeep Tallada

SCALE: 1.00

ALTIUM DESIGNER VERSION:
18.1.9.240

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